

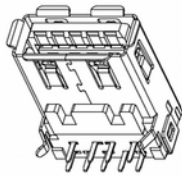
## USB 3.0 Steckverbinder, Typen A + B, Buchsen und Kabelstecker USB 3.0 Connectors, Types A + B, Jacks and Cable Plugs

### Technische Daten / Technical Data

Gehäuse	Kupferlegierung, vernickelt
Shell	Copper alloy, nickel plated
Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0, blau
Insulator	Thermoplastic, rated UL94 V-0, blue
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Oberfläche Lötanschluss	Verzinkt
Plating Solder Side	Tin plated
Lötbarkeit	IEC 60512-12A
Solderability	IEC 60512-12A
Durchgangswiderstand	< 30mΩ VBUS/GND im Auslieferungszustand
	< 50mΩ im Auslieferungszustand
Contact Resistance	< 30mΩ VBUS/GND initially
	< 50mΩ initially
Isolationswiderstand	> 10 <sup>8</sup> Ω
Insulation Resistance	> 10 <sup>8</sup> Ω
Spannungsfestigkeit	100V <sub>AC</sub>
Test Voltage	100V <sub>AC</sub>
Nennspannung	30V <sub>RMS</sub>
Voltage Rating	30V <sub>RMS</sub>
Nennstrom	1,8A VBUS/GND, 0,25A DATA
Current Rating	1.8A VBUS/GND, 0.25A DATA
Temperaturbereich	-55°C ... +85°C
Temperature Range	-55°C ... +85°C
Verarbeitung	Wellenlötverfahren
Processing	Wave soldering

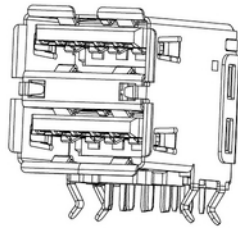


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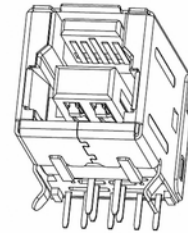
USB Type A Female

829-1-2-80



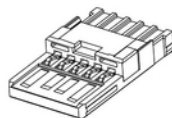
USB Type A Female 2x

829-4-2-80



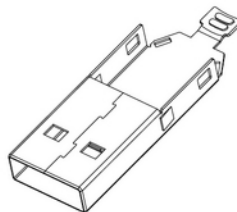
USB Type B Female

829-2-2-80



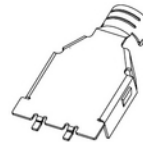
Kontakteinsatz

Connector Bit



Verbinderhülse

Bottom Cover



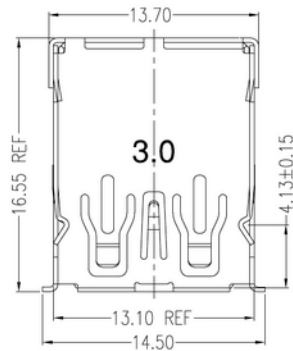
Obere Abdeckung

Top Cover

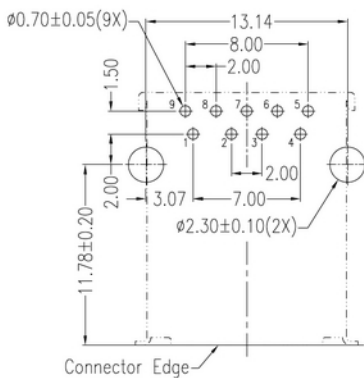
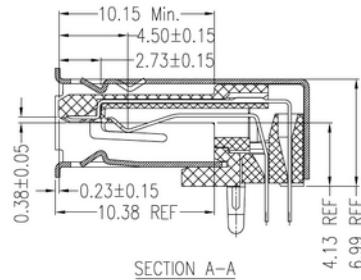
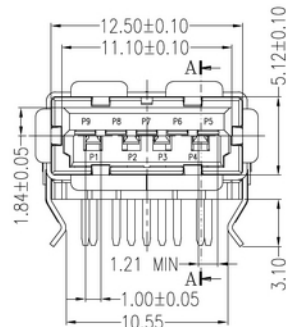
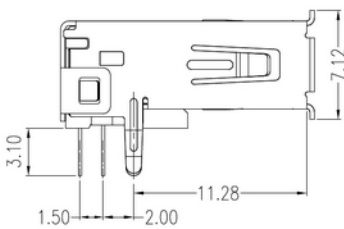
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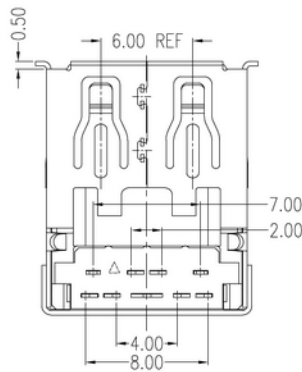
## USB 3.0 Steckverbinder, Typen A + B, Buchsen und Kabelstecker USB 3.0 Connectors, Types A + B, Jacks and Cable Plugs



PIN	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND-DRAIN
8	StdA_SSTX-
9	StdA_SSTX+



PCB LAYOUT T=1.60mm  
COMPONENT SIDE



Series

**829**

Type

**1**

1 Type A Buchse  
Type A female

Version

**2**

2 Einlöt-Version gewinkelt  
Right-angled solder-in version

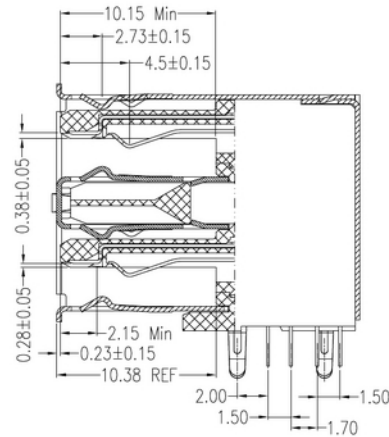
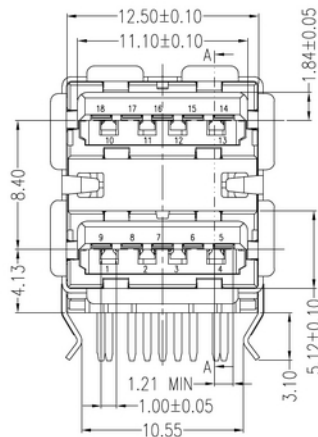
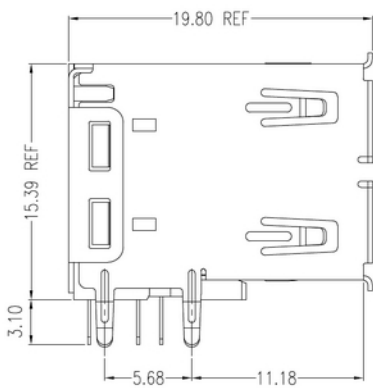
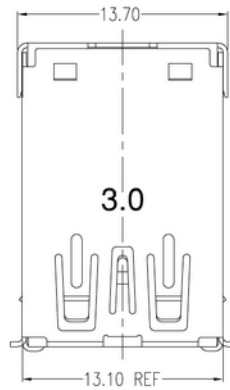
Plating

**80**

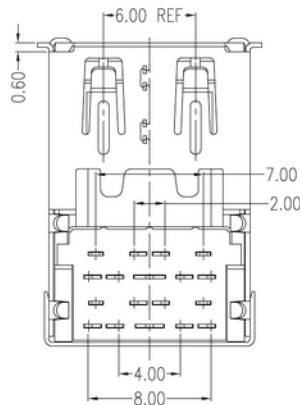
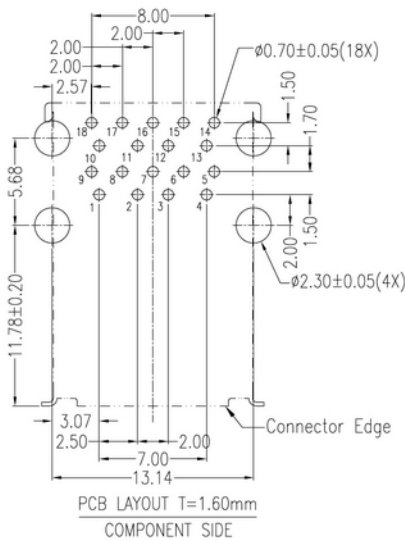
80 Vergoldet 30µ"  
Gold plated 30µ"

## USB 3.0 Steckverbinder, Typen A + B, Buchsen und Kabelstecker USB 3.0 Connectors, Types A + B, Jacks and Cable Plugs

PIN	SIGNAL NAME
1	10 VBUS
2	11 D-
3	12 D+
4	13 GND
5	14 StdA_SSRX-
6	15 StdA_SSRX+
7	16 GND-DRAIN
8	17 StdA_SSTX-
9	18 StdA_SSTX+



SECTION A-A



Series

**829**

Type

**4**

4 Type A Buchse zweifach  
Type A Female Dual Port

Version

**2**

2 Einlöt-Version gewinkelt  
Right-angled solder-in version

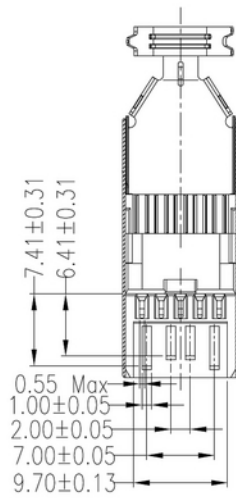
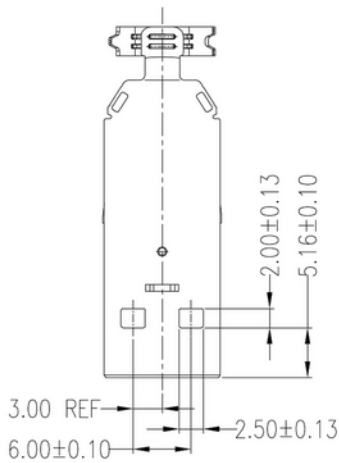
Plating

**80**

80 Vergoldet 30µ"  
Gold plated 30µ"



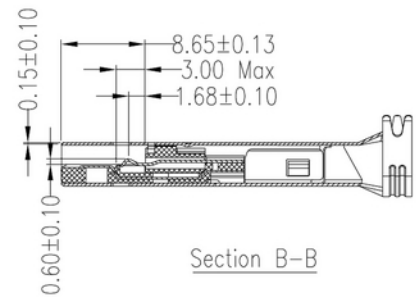
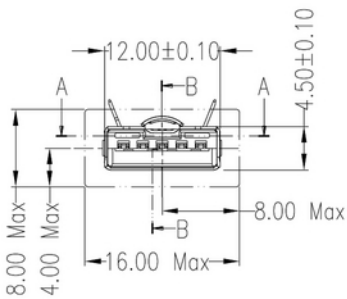
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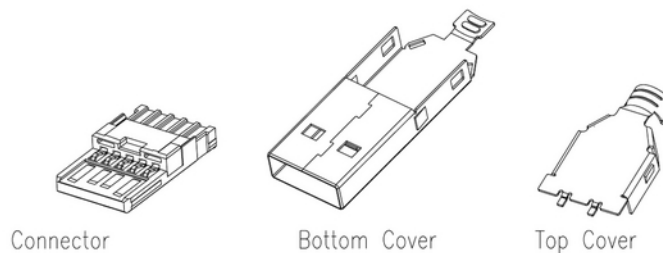
Section A-A



Pin Number	Signal Name
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND-DRAIN
8	StdA_SSTX-
9	StdA_SSTX+



Section B-B



Series	Type	Version	Diameter*	Plating
<b>829</b>	<b>8</b> 8 Type A Steckseite Type A male	<b>9</b> 9 Kabelstecker Cable plug	<b>4</b> 4 Kabeldurchmesser 4mm Outer Diameter 4mm 6 Kabeldurchmesser 6mm Outer Diameter 6mm	<b>80</b> 80 Vergoldet 30µ" Gold plated 30µ"

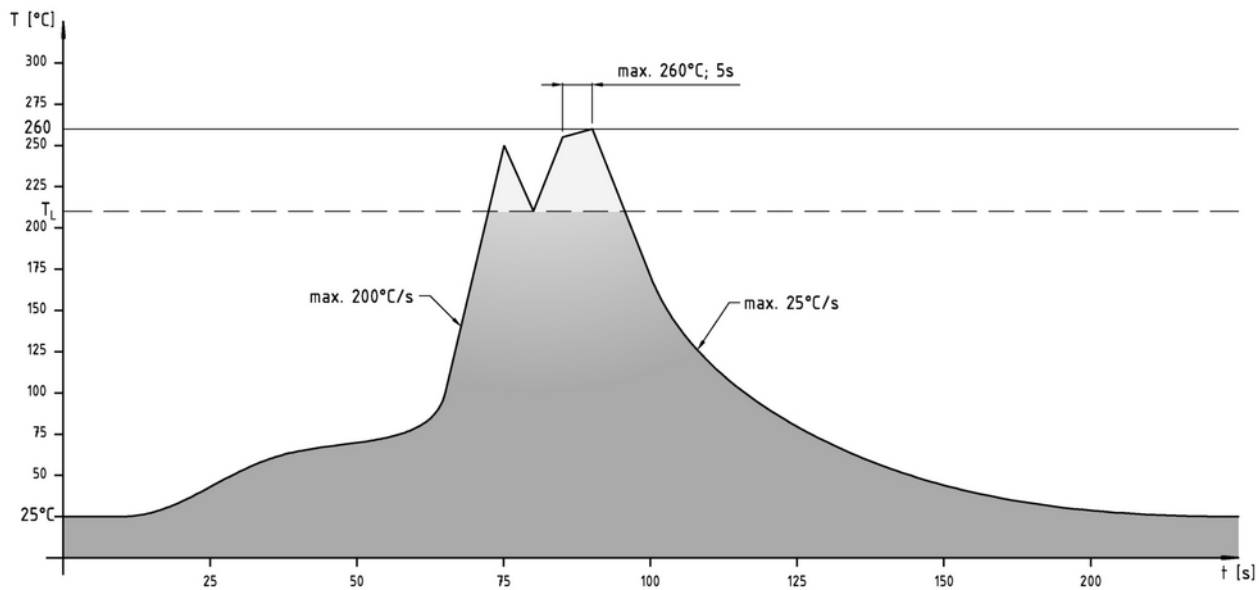
\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

## Informationen zum Wellen-Lötverfahren Wave Soldering Information

### Empfehlungen für das Wellenlötverfahren Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.  
*Items should be soldered at a solder temperature of 260°C in 5 seconds max.*

Empfohlenes Wellenlötprofil:  
*Recommended wave soldering profile:*



## Informationen zum Reflow-Lötverfahren Reflow Soldering Information

### Reflow-Löttempfehlung Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich $T_L$	217°C
Verweildauer oberhalb $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur $T_P$	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature $T_L$	217°C
Duration above $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature $T_P$	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 8min

